



Product Change Notification: ALAN-17QKTM046

Date:

21-Feb-2025

Product Category:

8-Bit Microcontrollers, KEELOQ® Decoder Devices

Notification Subject:

CCB 7364.007 Initial Notice: Qualification of Microchip Technology Gresham – Fab 4 (GRTM) as a new fabrication location for CS500, PIC12C509, PIC12C508, PIC16C62A, PIC16C73A, PIC16C711, PIC16C620, PIC16C662, PIC16C72, PIC16C66, PIC16C715, PIC14000, PIC16C923, PIC16C622, PIC17C44, PIC16C64A, PIC16C65A, PIC16C67, PIC16C54A, PIC16C710, PIC16C76, PIC16C77, PIC16C74A, PIC16C63, PIC16C621, PIC17C43, PIC17C42A, PIC16C554, PIC16C924, PIC16C558, PIC16C642, and PIC16LV54A in various packages.

Affected CPNs:

[ALAN-17QKTM046_Affected_CPN_02212025.pdf](#)

[ALAN-17QKTM046_Affected_CPN_02212025.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of Microchip Technology Gresham – Fab 4 (GRTM) as a new fabrication location for CS500, PIC12C509, PIC12C508, PIC16C62A, PIC16C73A, PIC16C711, PIC16C620, PIC16C662, PIC16C72, PIC16C66, PIC16C715, PIC14000, PIC16C923, PIC16C622, PIC17C44, PIC16C64A, PIC16C65A, PIC16C67, PIC16C54A, PIC16C710, PIC16C76, PIC16C77, PIC16C74A, PIC16C63, PIC16C621, PIC17C43, PIC17C42A, PIC16C554, PIC16C924, PIC16C558, PIC16C642, and PIC16LV54A in various packages.

Pre and Post Summary Changes:

	Pre Change	Post Change

Fabrication Site*	Microchip Technology Tempe – Fab 2 (TMGR)	Microchip Technology Gresham – Fab 4 (GRTM)
Wafer Size	8"	8"

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability and on time delivery performance by qualifying a new fabrication location (GRTM - FAB 4), which is a Microchip-owned facility that offers significant expansion potential to better meet future client demand. *Note: The attached file called Tempe_Fab2_IATF_Decertification is for the manufacturing site deactivation of Microchip Technology Tempe – Fab 2 (TMGR), contact your local Microchip sales office for inquiries.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: November 2025

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	February 2025					>	November 2025				
Work Week	05	06	07	08	09		44	45	46	47	48
Initial PCN Issue Date				X							
Qual Report Availability								X			
Final PCN Issue Date								X			

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: February 21, 2025: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[Tempe_Fab2_IATF_Decertification.pdf](#)
[PCN_ALAN-17QKTM046_Qual_Plan.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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PIC12C509, PIC12C508, PIC16C62A, PIC16C73A, PIC16C711, PIC16C620, PIC16C662, PIC16C72, PIC16C66, PIC16C715, PIC14000, PIC16C923, PIC16C622, PIC17C44, PIC16C64A, PIC16C65A, PIC16C67, PIC16C54A, PIC16C710, PIC16C76, PIC16C77, PIC16C74A, PIC16C63, PIC16C621, PIC17C43, PIC17C42A, PIC16C554, PIC16C924, PIC16C558, PIC16C642, and PIC16LV54A in various packages.

Affected Catalog Part Numbers (CPN)

PIC16C67-04/PQ

PIC16C66-04/SP

PIC16C66-20/SP

PIC16C74A-10/P

PIC17C44-16/P

PIC17C44-25/P

PIC16LC620-04/SOC29

PIC16C621-04/SS

PIC16C67-04/P

PIC16C64A-20/P

PIC16C711-04/SS

PIC16C64A-04/P

PIC17C44-16/L

PIC16C74A-04/P

PIC17C43-33/P

PIC16C62A-04/SP

PIC16C62A-20/SP

PIC16LC62A-04/SP

PIC16C73A-10/SP

PIC16C73A-20/SP

PIC16LC73A-04/SP

PIC16C67-20/P

PIC16LC710-04/SS

PIC16LC711-04/SS

PIC17C44-33/P

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PIC17C43-25/L

PIC16C74A-20/P

PIC16LC74A-04/P

PIC17C43-16/P

PIC17C43-25/P

PIC16C74A-04I/P

PIC16C74A-20I/P

PIC16C64A-20I/PT

PIC17C44-33I/L

PIC17C43-16I/L

PIC16C923-04I/PT

PIC16LC923-04I/PT

PIC17C42A-16I/PQ

PIC17C42A-25I/L

PIC16LC554-04I/SS

PIC16C63-20I/SP

PIC16C924-08I/PT

PIC16C554-04I/SO

PIC16C558-04I/SO

PIC16C642-04I/SO

PIC16LC924-04I/PT

PIC17C42A-33I/P

PIC16C642-20I/SO

PIC16C77-04I/P

PIC16C77-10I/P

PIC16C77-20I/P

PIC17LC44-08I/L

PIC16LC76-04I/SP

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PIC16C76-20I/SP

PIC16C76-04I/SP

PIC16C76-10I/SP

PIC16LV54A-02I/SS

PIC16C620-04I/SOVAO

PIC16C558-04I/SOVAO

PIC16LC554T-04I/SS

PIC16C554T-04I/SO

PIC16C54AT-04I/SO093

PIC16C73A-04/SP

PIC16C64A-10/PT

PIC16LC923-04/PT

PIC17C44-25/L

PIC17C44-33/L

PIC17C43-16/L

PIC17C42A-16/L

PIC17C42A-25/L

PIC16C554-04/SO

PIC16C554-20/SO

PIC17C42A-25/P

PIC17C42A-33/P

PIC16LC67-04/PT

PIC17C42A-16/PQ

PIC17C42A-25/PQ

PIC16LC554-04/SS

PIC16C77-20/PQ

PIC16C63-04/SP

PIC17C42A-16/P

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PIC16C76-04/SP

PIC16C76-10/SP

PIC16C76-20/SP

PIC16C65A-20/P

PIC16C63-10/SP

PIC16C63-20/SP

PIC16C65A-04/P

PIC16C65A-10/P

PIC16LC65A-04/P

PIC16LC642-04/SO

PIC16C924-04/PT

PIC16LC924-04/PT

PIC16C65A-20/PQ

PIC16C77-04/P

PIC16C77-20/P

PIC16C924-08/PT

PIC16C72-20/SP

PIC16C558-04/SO

PIC16C558-20/SO

PIC16LC558-04/SO

PIC16C72-04/SP

HCS500/SM

PIC16C54A-04/P428

PIC16C54A-04/P

PIC16C54A-20/P

PIC16C620-04/P

PIC16C620-20/P

PIC16C622-04/P

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PIC16C554-04/P

PIC16C558-04/P

PIC16C558-20/P

PIC16C710-04/P

PIC16C710-20/P

PIC16C711-04/P054

PIC16C711-04/P

PIC16C711-20/P

PIC16LC711-04/P

PIC16C715-04/P

PIC16C715-20/P

PIC16C711-04/S

PIC16LC77-04I/PT

HCS500-I/P

PIC12C509-04I/P

PIC12C508-04I/P

PIC16C62A-20I/SO

PIC16C73A-10I/SO

PIC16C73A-20I/SO

PIC16LC73A-04I/SO

PIC16C711-20I/SO

PIC16LC711-04I/SO

PIC16C620-04I/SO

PIC16C662-04I/P

HCS500-I/SM

PIC12C509-04I/SM

PIC16C72-10I/SS

PIC16C73A-04I/SO

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PIC12C508-04I/SM

PIC16C66-04I/SO

PIC16C715-04I/SO

PIC14000-04I/SS

PIC14000-20I/SS

PIC16LC923-04I/L

PIC14000-04I/SO

PIC14000-04I/SP

PIC16C622-04I/SO

PIC17LC44-08I/PT

PIC17C44-16I/PQ

PIC16C64A-04I/L

PIC16C65A-20I/L

PIC16C715-20I/SO

PIC16C64A-10I/L

PIC16C67-20I/L

PIC16C64A-20I/L

PIC16C66-10I/SO

PIC16C66-20I/SO

PIC16LC66-04I/SO

PIC16LC54A-04I/SO

PIC16C54A-04I/SO

PIC16LV54A-02I/SO

PIC16C710-04I/SO

PIC16C76-04I/SO

PIC16C76-10I/SO

PIC16C76-20I/SO

PIC16C67-04I/L

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PIC16C77-10I/L

PIC16C77-20I/L

PIC16LC77-04I/L

PIC16C67-04I/PQ

PIC16LC67-04I/PQ

PIC16C711-04I/SO

PIC17C44-16I/PT

PIC16C74A-04I/L

PIC16C74A-20I/L

PIC16C63-20I/SO

PIC16LC64A-04I/PQ

PIC16C74A-04I/PQ

PIC16C74A-20I/PQ

PIC16LC54A-04I/SS

PIC17LC44-08I/PQ

PIC16C72-04I/SO

PIC16C621-04I/SS

PIC16C66-20I/SP

PIC16C72-10I/SO

PIC16C715-04I/SS

PIC16C715-20I/SS

PIC17C44-16I/P

PIC16C62A-04I/SP

PIC16LV54A-02I/SO050

PIC17C44-25I/P

PIC17C44-33I/P

PIC16C64A-04I/P

PIC16C711-20I/SS

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PIC16C711-04I/SS

PIC16LC711-04I/SS

PIC16C77-04I/PT

PIC16C77-20I/PT

PIC16LC64A-04I/P

PIC16C66-04I/SP

PIC16C73A-04I/SP

PIC16C73A-10I/SP

PIC16C73A-20I/SP

PIC16C64A-04I/P053

PIC16C711-04I/SSVAO

PIC16C54A-04I/P

PIC16C62A-04I/SOVAO

PIC16C72-04I/SOVAO

PIC16C554-04I/P

PIC16C558-04I/P

PIC16C710-04I/P

PIC16C711-04I/P

PIC16C711-20I/P

PIC16LC711-04I/P

PIC16C715-04I/P

PIC16C715-20I/P

PIC16C711T-04/SO

PIC12C508T-04/SM

PIC14000T-04/SO

PIC16C715T-04/SO

PIC16C711T-20/SO

PIC16LC711T-04/SO

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PIC16C67T-20/L

PIC16LC711T-04/SS

PIC14000T-04/SSC01

PIC16LC554T-04/SS

PIC16C554T-04/SO

PIC16LC642T-04/SO

PIC16C67T-04I/L

PIC16C54AT-04I/SO

PIC16C711T-04I/SO

PIC16LC711T-04I/SO

PIC16C74AT-04I/L

PIC14000T-04I/SO

PIC16C711T-04I/SS

PIC16LV54AT-02I/SO050

PIC12C509T-04I/SM030

PIC16C54AT-04I/SO071

PIC16C711T-04I/SSVAO

PIC12C509-04E/SM

PIC12C508-04E/SM

PIC16C63-04E/SO

PIC16C711-20E/P

PIC16C64A-04E/L

PIC16C74A-20E/P

PIC16C73A-20E/SP

PIC16C711-04E/SO

PIC16C711-20E/SO

PIC16C558-04E/P

PIC16C72-20E/SP

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PIC16C76-20E/SP

PIC16C715-20E/SOVAO

PIC12C509-04/P

PIC12C508-04/P

PIC12C509-04/SM

PIC16C622-04/SO

PIC16C76-20/SO

PIC14000-04/SP

PIC16C63-20/SO

PIC16C715-20/SO

PIC16LC715-04/SO

PIC16C76-04/SO

PIC16C76-10/SO

PIC16C620-04/SO

PIC12C508-04/SM

PIC16C62A-04/SO

PIC16LC923-04/L

PIC16C73A-04/SO

PIC16C73A-20/SO

PIC16C54A-10/SO

PIC14000-04/SO

PIC14000-20/SO

PIC16C662-04/L

PIC16C54A-04/SO

PIC16LC924-04/L

PIC16C711-04/SO

PIC16C711-20/SO

PIC16LC711-04/SO

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PIC16C64A-20/L

PIC16LC64A-04/L

PIC16C62A-04/SS

PIC16C66-04/SO

PIC16C66-10/SO

PIC16C66-20/SO

PIC16C710-04/SO

PIC16C65A-04/L

PIC16C65A-10/L

PIC16C65A-20/L

PIC16C63-04/SO

PIC16C63-10/SO

PIC16C642-20/SP

PIC17C43-16/PQ

PIC17C44-16/PQ

PIC17C44-25/PQ

PIC16C77-20/L

PIC16LC77-04/L

PIC16LC54A-04/SO

PIC16C74A-04/L

PIC16C64A-20/PQ

PIC16C924-08/L

PIC16C74A-10/L

PIC16C74A-20/L

PIC16LC74A-04/L

PIC16C77-04/L

PIC16C77-10/L

PIC16C64A-04/L

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PIC16C72-04/SO

PIC17C44-16/PT

PIC17C44-33/PT

PIC16C715-04/SO

PIC16C67-20/PQ

PIC16C924-04/L

PIC16C923-04/L

PIC16C67-20/L

PIC16LC67-04/L

PIC16C64A-04/PQ

PIC16C64A-10/PQ



QUALIFICATION PLAN SUMMARY

PCN #: ALAN-17QKTM046

**Date:
February 11, 2025**

Qualification of Microchip Technology Gresham – Fab 4 (GRTM) as a new fabrication location for CS500, PIC12C509, PIC12C508, PIC16C62A, PIC16C73A, PIC16C711, PIC16C620, PIC16C662, PIC16C72, PIC16C66, PIC16C715, PIC14000, PIC16C923, PIC16C622, PIC17C44, PIC16C64A, PIC16C65A, PIC16C67, PIC16C54A, PIC16C710, PIC16C76, PIC16C77, PIC16C74A, PIC16C63, PIC16C621, PIC17C43, PIC17C42A, PIC16C554, PIC16C924, PIC16C558, PIC16C642, and PIC16LV54A in various packages.

Purpose:

Qualification of Microchip Technology Gresham – Fab 4 (GRTM) as a new fabrication location for CS500, PIC12C509, PIC12C508, PIC16C62A, PIC16C73A, PIC16C711, PIC16C620, PIC16C662, PIC16C72, PIC16C66, PIC16C715, PIC14000, PIC16C923, PIC16C622, PIC17C44, PIC16C64A, PIC16C65A, PIC16C67, PIC16C54A, PIC16C710, PIC16C76, PIC16C77, PIC16C74A, PIC16C63, PIC16C621, PIC17C43, PIC17C42A, PIC16C554, PIC16C924, PIC16C558, PIC16C642, and PIC16LV54A in various packages. This is a Grade 1 qualification

CCB No.:

7364.007 and 7413.006

<u>Misc.</u>	Assembly site	MTAI
	BD Number	A-056779 Rev B - Temp BD
	MP Code (MPC)	970731N3XC04
	Part Number (CPN)	PIC16C73A/PIC16FR73A/PIC16LC73A/PIC16LFR73A
	MSL information	1
	Assembly Shipping Media	Tube
	Base Quantity Multiple (BQM)	27
<u>Lead-Frame</u>	Paddle size	200x240 mils
	Material	CDA194
	DAP Surface Prep	Bare Cu
	Lead-lock	Yes
	Part Number	10102807
	Lead Plating	Matte Sn
<u>Bond Wire</u>	Material	CuPdAu
<u>Die Attach</u>	Part Number	3280
	Conductive	Yes
<u>MC</u>	Part Number	G600
<u>PKG</u>	Package Type	SOIC
	Pin/Ball Count	28L
	PKG width/size	.300in

Test Name	Conditions	Reliability Stress Read Point Grade 1: -40°C to +125°C (MCHP E Temp)	Pre & Post Reliability Stress Test Temperature Grade 1: -40°C to +125°C (MCHP E Temp)	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Standard Pb-free Solderability	J-STD-002D ; Perform 8 hours of steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages.			22	5	1	27	0	5	Standard Pb-free solderability is the requirement.
Wire Bond Pull - WBP	Mil. Std. 883-2011			5	0	1	5	0	5	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001			5	0	1	5	0	5	30 bonds from a min. 5 devices.
Physical Dimensions	Measure per JESD22 B100 and B108			10	0	3	30	0	5	
External Visual	Mil. Std. 883-2009/2010			All devices prior to submission for qualification testing	0	3	ALL	0	5	
HTSL (High Temp Storage Life)	JESD22-A103 +125°C, +150°C or +175°C 2x Stress	1st Readpoint: Grade 1: 500 hrs (+175°C) or 1000 hrs (150°C) 2nd Readpoint: Grade 1: 1000 hrs (+175°C) or 2000 hrs (150°C)	Grade 1: +25°C, +85°C, +125°C	45	5	3	150	0	21 - 167	Perform per the requirements in AEC-Q100/Q101. Spares should be properly identified.
Preconditioni ng - Required for surface mount devices	J-STD-020 JESD22-A113 +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD- 020E for package type.		Grade 1: +25°C	231 + 45	15 + 5	3	738 + 50	0	15	Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test.
HAST	JESD22-A101 or A110 +130°C/85% RH for 96 hrs or +110°C/85%RH for 264 hrs 2x Stress	1st Readpoint: Grade 1: 96 hrs (+130°C/85% RH) or 264 hrs (+110°C/85%RH) 2nd Readpoint:	Grade 1: +25°C, +85°C, +125°C	77	5	3	246	0	10 - 22	Perform per the requirements in AEC-Q006. Spares should be properly identified. Use the parts which have gone through Pre- conditioning.
uHAST	JESD22-A102, A118, or A101 +130°C/85% RH for 96 hrs or +110°C/85% RH for 264 hrs	Grade 1: 96 hrs (+130°C/85% RH) or 264 hrs (+110°C/85% RH)	Grade 1: +25°C	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre- conditioning.
Temp Cycle	JESD22-A104 and Appendix 3 -55°C to +125°C, -55°C to +150°C	1st Readpoint: Grade 1: 1000 cycles (-55°C	Grade 1: +25°C, +85°C, +125°C	77	5	3	246	0	15 - 120	Perform per the requirements in AEC-Q006. Spares should be properly identified.
Wire Bond Integrity (AEC-Q006 Requirement s)	AEC-Q006							See Special Instructions		Wire pull / ball shear is performed after stress testing and decapsulation.

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Test	Number of Lots	Sample Size per Lot	Total Samples	Conditions
ELFR	3	800	2400	48 hours @ 125°C
DLT	3	77	231	1000 Hours @ 125°C
Retention Bake	3	231	693	1008 hours @ 150°C
ESD (HBM)	1	12	12	3 each @ ±250V, ±500V, ±1KV & ±2KV
ESD (CDM)	1	9	9	3 each @ ±250V, ±500V, ±750V
Latch Up	1	12	12	6 room, 6 125°C AECQ100-004
Electrical Distribution	3	10	30	Data log parameters at room, hot, and cold temperatures at Vcc min/max and Frequency min/max.



Date: January 30, 2025

RE: Tempe (Fab 2) Wafer Fabrication Facility ISO/IATF Decertification

IATF Certificate: 08435-2002-AQ-HOU-IATF-33RSTM

On December 2, 2024, Microchip announced manufacturing restructuring plans that include the closure of the Tempe (Fab 2) Wafer Fabrication Facility.

This memo is to further announce that as part of the facility closure, its active IATF-16949 certificate will be withdrawn, in early Q3, 2025. Additionally, the facility will be removed from Microchip's Corporate ISO-9001 certificate by the end of 2025.

Microchip is committed to ensuring product quality during the entire time that Fab 2 remains operational. All established and certified process control measures remain in place and adherence to these practices will continue for the life of the fab, regardless of the status of IATF-16949 certification. Additionally, all Microchip devices are 100% electrically tested, with only known good products shipped to customers.

Please contact your local [Microchip Sales Office](#) with questions or concerns regarding this notification.

Regards,
Microchip Corporate Quality Systems

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